Absolute Maximum Ratings at T_j=25 unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	650	V
Gate-source voltage	V_{GS}	±30	V
Continuous drain current[1], T_C=25 °C	I_D	8	A
Continuous drain current[1], T_C=100 °C		5	
Pulsed drain current[2], T_C=25 °C	$I_{D,\ pulse}$	24	A
Continuous diode forward current[1], T_C=25 °C	I_S	8	A
Diode pulsed current[2], T_C=25 °C	$I_{S,\ pulse}$	24	A
Power dissipation[3], T_C=25 °C	P_D	26	W
Single pulsed avalanche energy[5]	E_{AS}	125	mJ
MOSFET dv/dt ruggedness, V_{DS} 480 V	dv/dt	50	V/ns
Reverse diode dv/dt, V_{DS} 480 V, I_{SD} D	dv/dt	15	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	R	4.81	°C/W
Thermal resistance, junction-ambient[4]	R	62.5	°C/W

Electrical Characteristics at T_j=25 unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	650			V	V_{GS}=0 V, I_D=250 A
		700				V_{GS}=0 V, I_D=250 A, T_j=150 °C
Gate threshold voltage	$V_{GS(th)}$	2.9		3.9	V	V_{DS}=V_{GS}, I_D=250 A
Drain-source on-state resistance	$R_{DS(ON)}$		0.5	0.58		V_{GS}=10 V, I_D=4 A
			1.4			V_{GS}=10 V, I_D=4 A, T_j=150 °C
Gate-source leakage current	I_{GSS}			100	nA	V_{GS}=30 V
				-100		V_{GS}=-30 V
Drain-source leakage current	I_{DSS}			1	A	V_{DS}=650 V, V_{GS}=0 V
Gate resistance	R_G		47			f= 1 MHz, Open drain

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}				pF	V_{GS}=0 V, V_{DS}=50 V, 00 kHz
Output capacitance	C_{oss}		41.7		pF	
Reverse transfer capacitance	C_{rss}		3.1		pF	
Turn-on delay time	$t_{d(on)}$		26.4		ns	V_{GS}=10 V, V_{DS}=400 V, R_G=3 I_D=4 A
Rise time	t_r		17.9		ns	
Turn-off delay time	$t_{d(off)}$		56.2		ns	
Fall time	t_f		14		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		8.6		nC	V_{GS}=10 V, V_{DS}=400 V, I_D=4 A
Gate-source charge	Q_{gs}		2.2		nC	
Gate-drain charge	Q_{gd}		3.8		nC	
Gate plateau voltage	$V_{plateau}$		5.7		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V_{SD}			1.3	V	I_S=8 A, V_{GS}=0 V
Reverse recovery time	t_{rr}		214.3		ns	, I_S=4 A,
Reverse recovery charge	Q_{rr}		1.7		C	
Peak reverse recovery current	I_{rrm}		16.1		A	

Note

1) Calculated continuous current based on maximum allowable junction temperature.
2) Repetitive rating; pulse width limited by max. junction temperature.
3) Pd is based on max. junction temperature, using junction-case thermal resistance.
4) The value of R is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
5) V_{DD}=100 V, V_{GS}=10 V, L=79.9 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

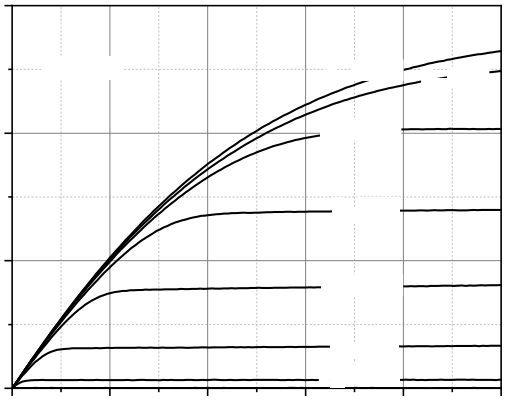

Figure 1. Typ. output characteristics

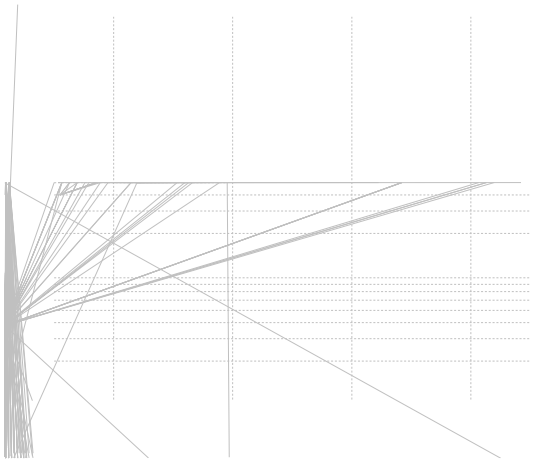

Figure 2. Typ. transfer characteristics

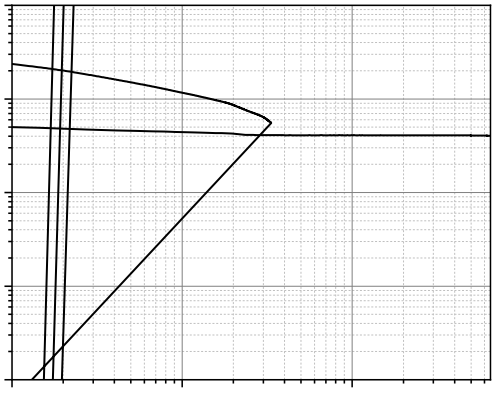

Figure 3. Typ. capacitances

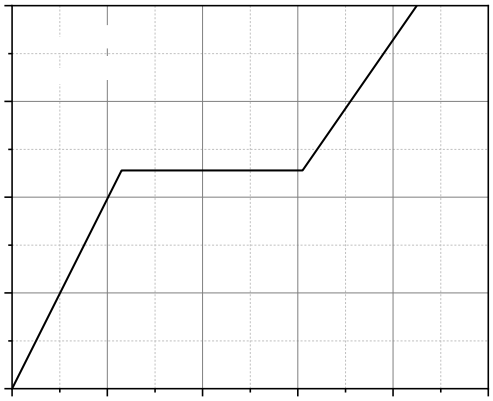

Figure 4. Typ. gate charge

Figure 5. Drain-source breakdown voltage

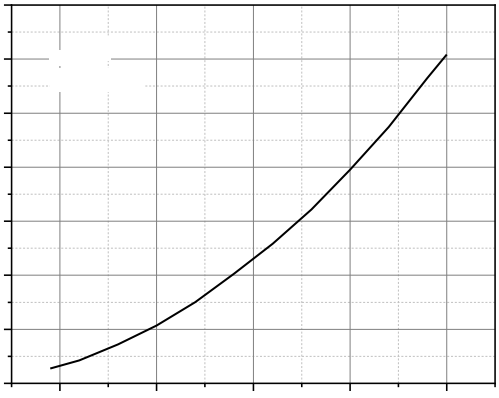

Figure 6. Drain-source on-state resistance

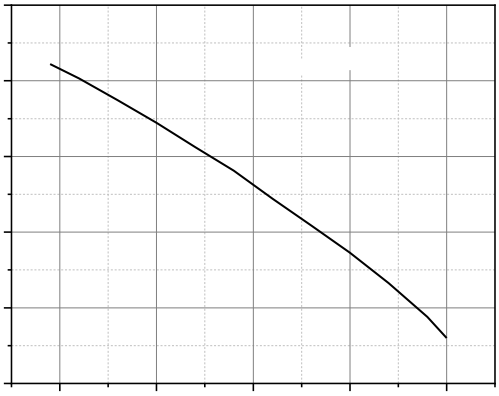

Figure 7. Threshold voltage

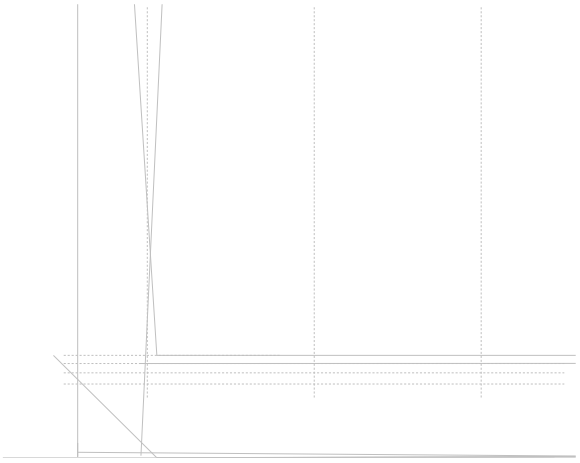

Figure 8. Forward characteristic of body diode

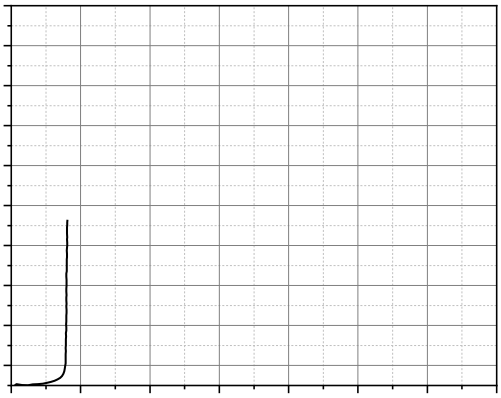

Figure 9. Drain-source on-state resistance

Figure 10. Drain current

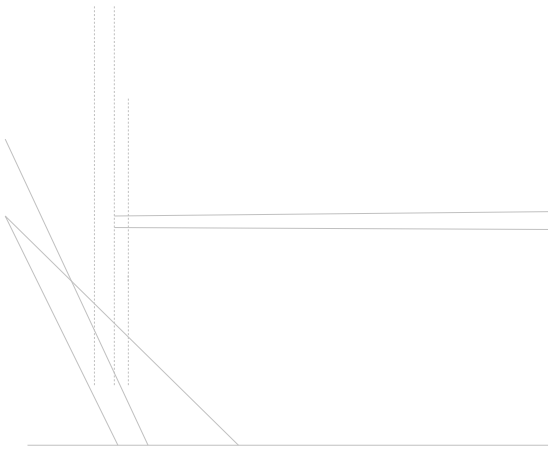

Figure 11. Safe operation area T_C=25 °C

Test circuits and waveforms

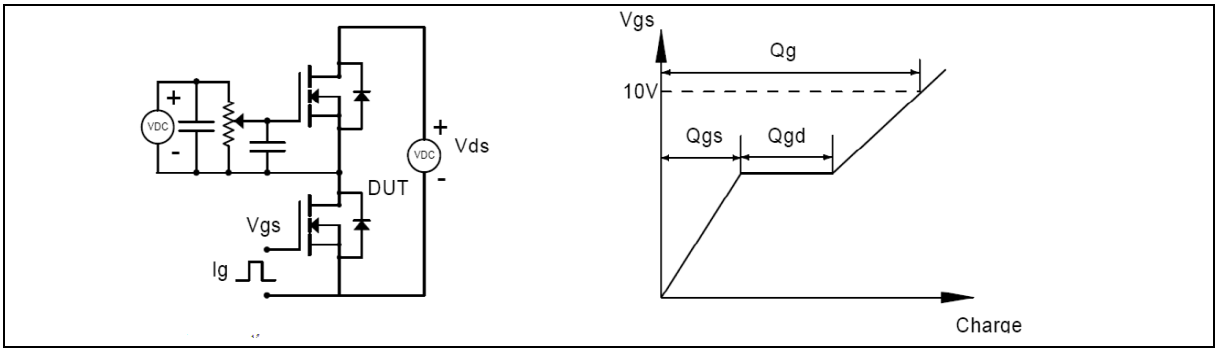

Figure 1. Gate charge test circuit & waveform

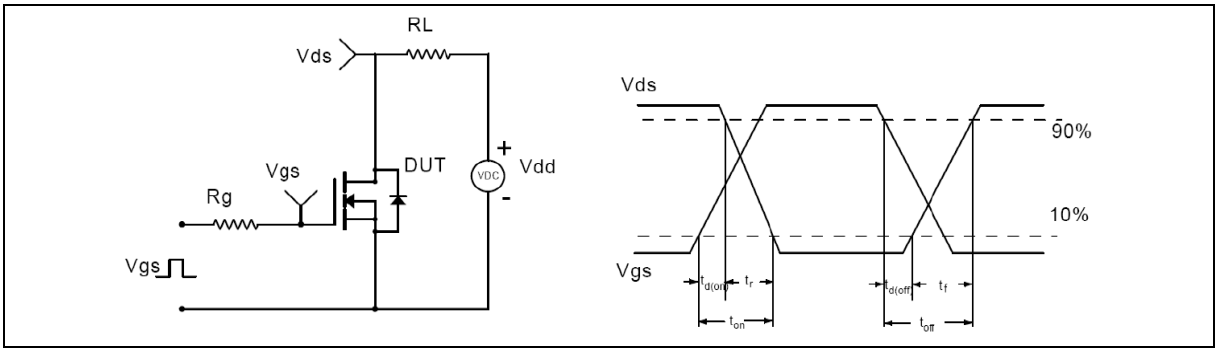

Figure 2. Switching time test circuit & waveforms

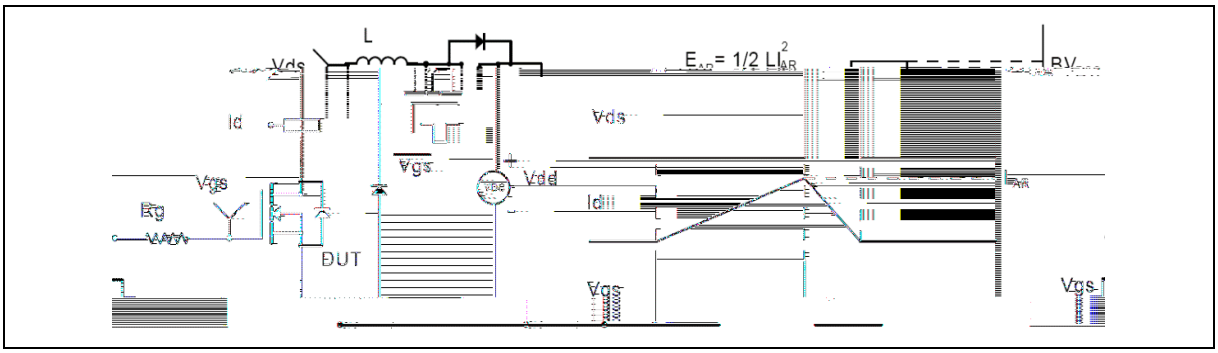

Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

Figure 4. Diode reverse recovery test circuit & waveforms

Ordering Information

Package Type	Units/ Tube	Tubes/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO220F-C	50	20	1000	6	6000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG65R580FTF	TO220F	yes	yes	yes